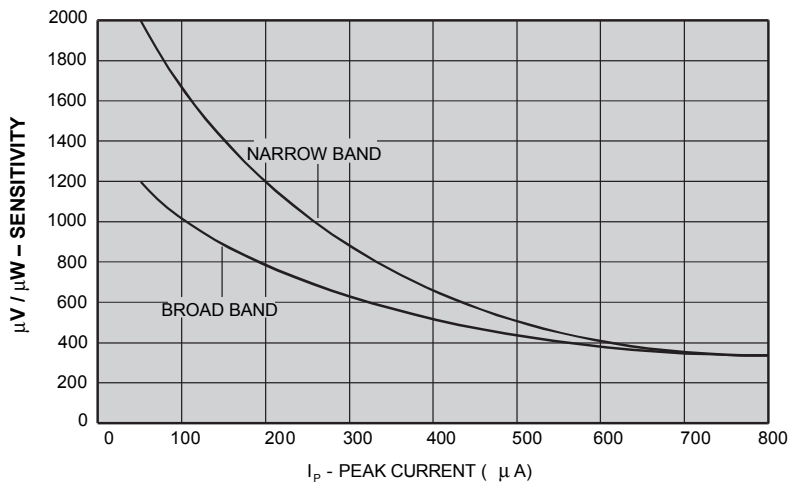
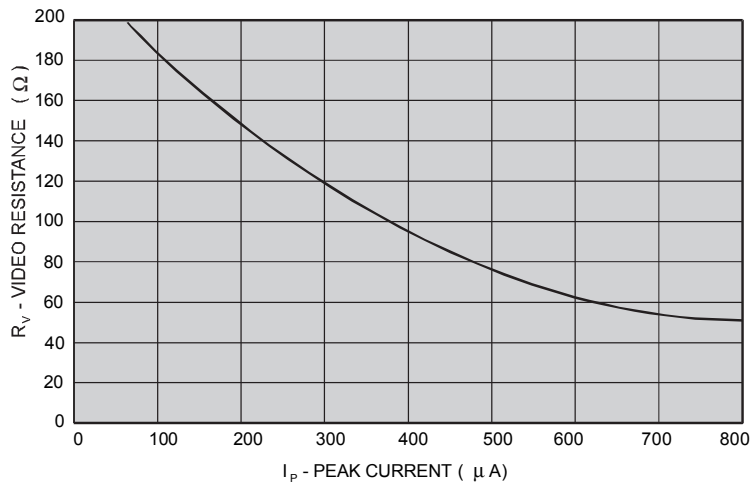
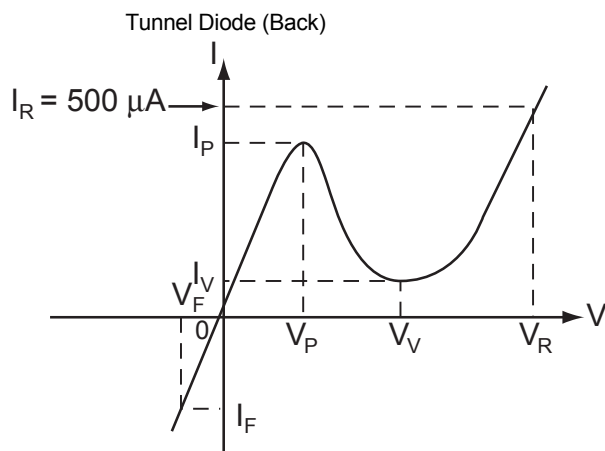


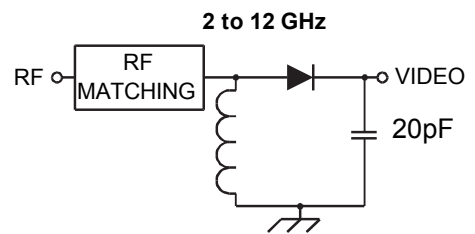
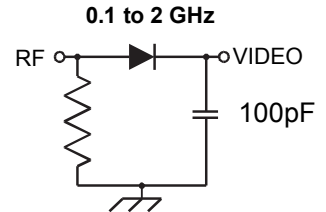
Tunnel Diodes						
Part Number	Case Style	Ip range (μA)	Iv max (μA)	Vr (typ) Ir= 500μA (mV)	Vf(max) If= 3mA (mV)	Ct (max) (pF)
MP1101	C2	0 - 100	40	425	150	0.2
MP1100	C2	0 - 100	40	425	145	0.25
MP1102	C2	0 - 100	40	425	145	0.3
MP1103	E1	0 - 100	40	425	145	0.4
MP1104	S1	0 - 100	40	425	145	0.5
MP1105	P1	0 - 100	40	425	145	0.7
MP1201	C2	100 - 200	80	425	135	0.2
MP1200	C2	100 - 200	80	425	130	0.25
MP1202	C2	100 - 200	80	425	125	0.3
MP1203	E1	100 - 200	80	425	130	0.4
MP1204	S1	100 - 200	80	425	130	0.5
MP1205	P1	100 - 200	80	425	130	0.7
MP1301	C2	200 - 300	100	425	125	0.2
MP1300	C2	200 - 300	100	425	125	0.25
MP1302	C2	200 - 300	100	425	120	0.3
MP1303	E1	200 - 300	100	425	120	0.4
MP1304	S1	200 - 300	100	425	120	0.5
MP1305	P1	200 - 300	100	425	120	0.7
MP1451	C2	300 - 450	150	425	120	0.2
MP1450	C2	300 - 450	150	425	120	0.25
MP1452	C2	300 - 450	150	425	120	0.3
MP1453	E1	300 - 450	150	425	115	0.4
MP1454	S1	300 - 450	150	425	115	0.5
MP1455	P1	300 - 450	150	425	115	0.7
MP1601	C2	450 - 600	225	425	115	0.2
MP1600	C2	450 - 600	225	425	110	0.25
MP1602	C2	450 - 600	225	425	105	0.3
MP1603	E1	450 - 600	225	425	110	0.4
MP1604	S1	450 - 600	225	425	110	0.5
MP1605	P1	450 - 600	225	425	110	0.7



Characteristic Curve



Typical Detector Circuits



Chip (C2) Assembly Notes

ThermoCompression Wedge Bonding:

1. Use 0.7 mil gold wire.
2. Tip temperature = 180°C MAX.
3. Stage temperature = 160°C MAX.

Die attach

1. Silver epoxy with a maximum cure temperature of 125°C is recommended.

Package Assembly Notes

Lead Attach

1. 230°C Solder attach for 5 sec MAX.

CAUTION —

Extremely Static Sensitive Devices

Notes

1. Chip top contact is cathode.
2. Detected output will be negative from the cathode.